PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT4851195

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
CHI-RUEI YEH	11/12/2015
CHIH-LIN WANG	11/12/2015
KANG-MIN KUO	11/12/2015

RECEIVING PARTY DATA

Name:	TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.	
Street Address:	NO. 8, LI-HSIN RD. 6	
Internal Address:	HSINCHU SCIENCE PARK	
City:	HSINCHU	
State/Country:	TAIWAN	
Postal Code:	300-78	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	15911884

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ATTORNEY DOCKET NUMBER:	20150528 / 24061.3445US02	
NAME OF SUBMITTER:	JANIE MARTINEZ-HOLM	
SIGNATURE:	/Janie Martinez-Holm/	
DATE SIGNED:	03/05/2018	

Total Attachments: 2

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PATENT REEL: 045108 FRAME: 0080 504804463

Attorney Docket No.: 0941-3274PUS1

ASSIGNMENT

WHEREAS, Chi-Ruei YEH, Chih-Lin WANG, and Kang-Min KUO

hereafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: SEMICONDUCTOR DEVICE STRUCTURE AND METHOD FOR FORMING THE

SAME

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Filed: November 13, 2015 Serial No. 14/940,832 Executed on: November 12, 2015

WHEREAS, <u>Taiwan Semiconductor Manufacturing Co., Ltd.</u>, of <u>No. 8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu 300-78, Taiwan R.O.C.</u> hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same;

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

PATENT REEL: 033068 FRAME: 0282

2015/11/12 (hi Ruei YEH

Name: Chi-Ruei YEH

(Last name: YEH)

(Last name: KUO)